

This document explains the function of the Backplane, its schematic level design, and its board level design

Backplane

Backplane Design

Revision: 3.1.1

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1 Introduction

This document explains how the Backplane will fulfil the following Functions and Requirements. This document refers to the Backplane version 3.1.0.

1.1 Function

The Backplane connects all the subsystems of the satellite together via a parallel bus and interchangeable cards.

1.2 Requirements

The system requirements and EPS design requirements can be found [on GitHub](#).

2 Detailed Description

This section references the Backplane [schematic](#). Page numbers will be listed and may have coordinates listed (number and letter combination found around the frame).

2.1 Functional Block Diagram

The block diagram can be found on the first page of the schematic.

2.1.1 Card Slots

The Backplane has eight slots connected in parallel. Each slot is electrically identical. Any card is compatible with every slot.

2.1.2 Separation Switch

The separation switch connects via a connector to the Backplane.

2.2 Schematic

2.2.1 Isolated Grounds

On page 2 of the schematic (D1), are the two isolated grounds found on the Backplane. Power ground (*PGND*) is directly connected to the card. The other grounds are shorted to *PGND* using a 0Ω resistor rated up to 2A, the expected current is less than 50mA each. Chassis ground (*CHASSIS[1:2]*) is connected to the conductive Mechanical Features including bolt holes.

2.2.2 Separation Switching

There are two identical connectors to connect to the separation switches. The CubeSat requirements specify at least one separation switch, either or both connectors can be used. The switch is normal open and shorts to *PGND* when depressed.

2.2.3 Card Connectors

Each card connector is a PCIe socket with 98 pins. See Table 1 for the pin allocation. Each power rail has two pins in parallel which allows loads rated up to 1A. Each I2C and SPI data signal has two pins in parallel which increases redundancy¹.

Table 1: Connector Pinout

Pins	Pin Name	Description
A1, B1	PR_3.3V-0	Power Rail 3.3V - Channel 0
A2, B2	PR_3.3V-1	Power Rail 3.3V - Channel 1
A3, B3	PR_3.3V-2	Power Rail 3.3V - Channel 2
A4, B4	PR_3.3V-3	Power Rail 3.3V - Channel 3
A5, B5	PR_3.3V-4	Power Rail 3.3V - Channel 4
A6, B6	PR_3.3V-5	Power Rail 3.3V - Channel 5

¹ REQ-009

Pins	Pin Name	Description
A7, B7	PR_3.3V-6	Power Rail 3.3V - Channel 6
A8, B8	PR_3.3V-7	Power Rail 3.3V - Channel 7
A9, B9	PR_3.3V-8	Power Rail 3.3V - Channel 8
A10, B10	PR_3.3V-9	Power Rail 3.3V - Channel 9
A11, B11	PR_3.3V-10	Power Rail 3.3V - Channel 10
A12, B12	PR_3.3V-11	Power Rail 3.3V - Channel 11
A13, B13	PR_3.3V-12	Power Rail 3.3V - Channel 12
A14, B14	PR_BATT-0	Power Rail Vbatt - Channel 0
A15, B15	PR_BATT-1	Power Rail Vbatt - Channel 1
A16, B16	PR_BATT-2	Power Rail Vbatt - Channel 2
A17, B17	PR_BATT-3	Power Rail Vbatt - Channel 3
A18, B18	PR_BATT-4	Power Rail Vbatt - Channel 4
A19, B19	PR_BATT-5	Power Rail Vbatt - Channel 5
A20, B20	PR_BATT-6	Power Rail Vbatt - Channel 6
A21-23 B21-29	PGND	Global ground potential.
A40, B40	PWR_CTRL_SW	Disconnects battery (active low), driven by deployment switch OR RBF pin
A43, B43	BUS_I2C0_SDA	I2C interfaces for bidirectional data exchange among high priority devices
A44, B44	BUS_I2C0_SCL	
A45, B45	BUS_I2C0_IRQ	
A30, B30	BUS_I2C1_SDA	I2C interfaces for bidirectional data exchange among low priority devices
A31, B31	BUS_I2C1_SCL	
A32, B32	BUS_I2C1_IRQ	
A37, B37	BUS_SPI_SCK	SPI interface to subsystem or direct access to remote serial device
A38, B38	BUS_SPI_MISO	
A39, B39	BUS_SPI_MOSI	
A42, B42	CTRL_SYNC	Global synchronization signal, driven by IHU
A33, B33	COM_SPI_SCK	Serial interface for dedicated communication with the Comms
A34, B34	COM_SPI_MISO	Serial interface for dedicated communication with the Comms Shared JTAG interface for subsystem software update via IFJR. Max 1 device at a time, normally high impedance
A35, B35	COM_SPI_MOSI	
A36, B36	COM_SPI_CS	
A46	BUS_JTAG_TCK	
A47	BUS_JTAG_TDI	Shared JTAG interface for subsystem software update via IFJR. Max 1 device at a time, normally high impedance
A48	BUS_JTAG_TDO	
A49	BUS_JTAG_TMS	
B46	BUS_JTAG_EN-0	JTAG_SEL_COMMS
B47	BUS_JTAG_EN-1	JTAG_SEL_PMIC
B48	BUS_JTAG_EN-2	
B49	BUS_JTAG_EN-3	
A24	GPIO-0	SPI_EN_CAM0
A25	GPIO-1	SPI_EN_CAM1
A26	GPIO-2	SPI_EN_CAM2 (Germination Chamber Camera)
A27	GPIO-3	PWM_LIGHTING (Germination Chamber Lighting)
A28	GPIO-4	PWM_HEATER (Germination Chamber Heater)
A29	GPIO-5	

Pins	Pin Name	Description
A41	GPI0-6	
B41	GPI0-7	

2.2.4 Mechanical Features

The Backplane mounts to the Structure using two bolts (page 5, D1) and the top and bottom edges. Each of the holes have a capacitor and resistor connecting to power ground which will absorb transients.

2.3 Board

The board shall be double layered with 2 oz copper and ENIG finish. The board shall be 1mm thick.

2.3.1 Layout Constraints

Unless specified in the following subsections, all signals shall use the default minimum parameters below. Signals in the following subsections do not include their sense signals unless specified. Trace width can be broken if a trace needs to bottleneck down to a pin, the bottleneck shall be minimized.

Trace width:	0.16mm
Vias:	Ø0.3mm, unlimited count
Separation:	0.16mm
Length:	unlimited

Devices with specific placement and routing considerations are called out on the schematic, see "CAD Note:"

2.3.1.1 Power Channels - PR_33V-[0:12], PR_BATT-[0:6]

Trace width:	0.5mm
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2.3.1.2 Power Ground - PGND

Trace width:	3.0mm
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2.3.1.3 Data Lines

Length:	Each node shall be length matched $\pm 10.0mm$
Stubs:	< 10.0mm

3 Testing

All tests shall be performed at room temperature and not under vacuum unless otherwise specified. If any modifications are performed, take note. Include enough information to understand circuit behavior and for others to replicate the results. Include any software written to execute the test and link it in the test notes section. Save all software, waveforms, etc. in a subfolder of the board's test folder for each test².

- Waveforms shall be captured whenever appropriate
- Have the event take fill the screen (for fast events, zoom in; for slow events, zoom out)
- Label each channel accurately
- Only have bandwidth limiting if necessary for the test (this applies to the oscilloscope and probe settings)
- If ringing or overshoot occurs, use a ground spring or differential probe

Results location: <https://github.com/CougsInSpace/CougSat1-Hardware/tree/master/CougSat1-Backplane/Testing/Backplane.3.0>

Common test instructions can be found on the [wiki](#).

3.1 Separation Switching

Results: Pass

Test Configuration: Howard

This test evaluates the circuit described in Separation Switching.

3.1.1 Test Instructions

Connect the separation switch to each connector. Measure the resistance between *PWR_CTRL_SW* and *PGND* in all switch states.

3.1.2 Test Data

Measure the resistance between <i>PWR_CTRL_SW</i> and <i>PGND</i> in both switch states.				
Switch State		Resistance	Passing Criteria	Pass / Fail
J5	J6			
Released	Released	$> 100M\Omega$	Resistance $> 10M\Omega$	Pass
Released	Depressed	0.8Ω	Resistance $< 10\Omega$	Pass
Depressed	Released	0.8Ω	Resistance $< 10\Omega$	Pass
Depressed	Depressed	0.6Ω	Resistance $< 10\Omega$	Pass

3.2 Continuity

Results: Pass

Test Configuration: Howard

² For test 3.1, place files in the subfolder "3.1" and so on

This test evaluates the circuit described in Card Connectors.

3.2.1 Test Instructions

Measure the resistance of each power channel and the power ground from Slot 0 to Slot 4 (from bottom to top slot). Measure on the card, at the connector.

3.2.2 Test Data

Measure the resistance between each power channel and the power ground from Slot 0 to Slot 7.			
Power Channel	Resistance	Passing Criteria	Pass / Fail
PGND	32mΩ	Resistance < 100mΩ	Pass
PR_3.3V-0	20mΩ	Resistance < 100mΩ	Pass
PR_3.3V-1	25mΩ	Resistance < 100mΩ	Pass
PR_3.3V-2	28mΩ	Resistance < 100mΩ	Pass
PR_3.3V-3	20mΩ	Resistance < 100mΩ	Pass
PR_3.3V-4	32mΩ	Resistance < 100mΩ	Pass
PR_3.3V-5	19.5mΩ	Resistance < 100mΩ	Pass
PR_3.3V-6	23.5mΩ	Resistance < 100mΩ	Pass
PR_3.3V-7	26.7mΩ	Resistance < 100mΩ	Pass
PR_3.3V-8	29mΩ	Resistance < 100mΩ	Pass
PR_3.3V-9	26mΩ	Resistance < 100mΩ	Pass
PR_3.3V-10	30mΩ	Resistance < 100mΩ	Pass
PR_3.3V-11	42mΩ	Resistance < 100mΩ	Pass
PR_3.3V-12	36mΩ	Resistance < 100mΩ	Pass
PR_BATT-0	42mΩ	Resistance < 100mΩ	Pass
PR_BATT-1	32mΩ	Resistance < 100mΩ	Pass
PR_BATT-2	32mΩ	Resistance < 100mΩ	Pass
PR_BATT-3	38mΩ	Resistance < 100mΩ	Pass
PR_BATT-4	16.5mΩ	Resistance < 100mΩ	Pass
PR_BATT-5	32mΩ	Resistance < 100mΩ	Pass
PR_BATT-6	30mΩ	Resistance < 100mΩ	Pass
PWR_CTRL_SW	112mΩ	Resistance < 300mΩ	Pass
BUS_I2C0_SDA	104mΩ	Resistance < 300mΩ	Pass
BUS_I2C0_SCL	115mΩ	Resistance < 300mΩ	Pass
BUS_I2C0_IRQ	107mΩ	Resistance < 300mΩ	Pass
BUS_I2C1_SDA	109mΩ	Resistance < 300mΩ	Pass
BUS_I2C1_SCL	102mΩ	Resistance < 300mΩ	Pass
BUS_I2C1_IRQ	109mΩ	Resistance < 300mΩ	Pass
BUS_SPI_SCK	103mΩ	Resistance < 300mΩ	Pass
BUS_SPI_MISO	101mΩ	Resistance < 300mΩ	Pass
BUS_SPI_MOSI	109mΩ	Resistance < 300mΩ	Pass
COM_SPI_SCK	105mΩ	Resistance < 300mΩ	Pass
COM_SPI_MISO	104mΩ	Resistance < 300mΩ	Pass
COM_SPI_MOSI	112mΩ	Resistance < 300mΩ	Pass
COM_SPI_CS	108mΩ	Resistance < 300mΩ	Pass
BUS_JTAG_TCK	114mΩ	Resistance < 300mΩ	Pass
BUS_JTAG_TDI	113mΩ	Resistance < 300mΩ	Pass
BUS_JTAG_TDO	113mΩ	Resistance < 300mΩ	Pass

Measure the resistance between each power channel and the power ground from Slot 0 to Slot 7.			
Power Channel	Resistance	Passing Criteria	Pass / Fail
BUS_JTAG_TMS	112mΩ	Resistance < 300mΩ	Pass
BUS_JTAG_EN-0	111mΩ	Resistance < 300mΩ	Pass
BUS_JTAG_EN-1	112mΩ	Resistance < 300mΩ	Pass
BUS_JTAG_EN-2	108mΩ	Resistance < 300mΩ	Pass
BUS_JTAG_EN-3	115mΩ	Resistance < 300mΩ	Pass
GPIO-0	112mΩ	Resistance < 300mΩ	Pass
GPIO-1	112mΩ	Resistance < 300mΩ	Pass
GPIO-2	111mΩ	Resistance < 300mΩ	Pass
GPIO-3	109mΩ	Resistance < 300mΩ	Pass
GPIO-4	113mΩ	Resistance < 300mΩ	Pass
GPIO-5	113mΩ	Resistance < 300mΩ	Pass
GPIO-6	119mΩ	Resistance < 300mΩ	Pass
GPIO-7	108mΩ	Resistance < 300mΩ	Pass

3.3 Isolation

Results: Pass

Test Configuration: Howard

This test evaluates the circuit described in Card Connectors.

3.3.1 Test Instructions

Measure the resistance of each net on the card connector to every other net.

3.3.2 Test Data

Measure the resistance of each net on the card connector to every other net.		
Net	Passing Criteria	Pass / Fail
PR_3.3V-0	All resistances > 10MΩ	Pass
PR_3.3V-1	All resistances > 10MΩ	Pass
PR_3.3V-2	All resistances > 10MΩ	Pass
PR_3.3V-3	All resistances > 10MΩ	Pass
PR_3.3V-4	All resistances > 10MΩ	Pass
PR_3.3V-5	All resistances > 10MΩ	Pass
PR_3.3V-6	All resistances > 10MΩ	Pass
PR_3.3V-7	All resistances > 10MΩ	Pass
PR_3.3V-8	All resistances > 10MΩ	Pass
PR_3.3V-9	All resistances > 10MΩ	Pass
PR_3.3V-10	All resistances > 10MΩ	Pass
PR_3.3V-11	All resistances > 10MΩ	Pass
PR_3.3V-12	All resistances > 10MΩ	Pass
PR_BATT-0	All resistances > 10MΩ	Pass
PR_BATT-1	All resistances > 10MΩ	Pass
PR_BATT-2	All resistances > 10MΩ	Pass
PR_BATT-3	All resistances > 10MΩ	Pass
PR_BATT-4	All resistances > 10MΩ	Pass
PR_BATT-5	All resistances > 10MΩ	Pass

Measure the resistance of each net on the card connector to every other net.		
Net	Passing Criteria	Pass / Fail
PR_BATT-6	All resistances > 10M Ω	Pass
PGND	All resistances > 10M Ω	Pass
PWR_CTRL_SW	All resistances > 10M Ω	Pass
BUS_I2C0_SDA	All resistances > 10M Ω	Pass
BUS_I2C0_SCL	All resistances > 10M Ω	Pass
BUS_I2C0_IRQ	All resistances > 10M Ω	Pass
BUS_I2C1_SDA	All resistances > 10M Ω	Pass
BUS_I2C1_SCL	All resistances > 10M Ω	Pass
BUS_I2C1_IRQ	All resistances > 10M Ω	Pass
BUS_SPI_SCK	All resistances > 10M Ω	Pass
BUS_SPI_MISO	All resistances > 10M Ω	Pass
BUS_SPI_MOSI	All resistances > 10M Ω	Pass
CTRL_SYNC	All resistances > 10M Ω	Pass
COM_SPI_SCK	All resistances > 10M Ω	Pass
COM_SPI_MISO	All resistances > 10M Ω	Pass
COM_SPI_MOSI	All resistances > 10M Ω	Pass
COM_SPI_CS	All resistances > 10M Ω	Pass
BUS_JTAG_TCK	All resistances > 10M Ω	Pass
BUS_JTAG_TDI	All resistances > 10M Ω	Pass
BUS_JTAG_TDO	All resistances > 10M Ω	Pass
BUS_JTAG_TMS	All resistances > 10M Ω	Pass
BUS_JTAG_EN-0	All resistances > 10M Ω	Pass
BUS_JTAG_EN-1	All resistances > 10M Ω	Pass
BUS_JTAG_EN-2	All resistances > 10M Ω	Pass
BUS_JTAG_EN-3	All resistances > 10M Ω	Pass
GPIO-0	All resistances > 10M Ω	Pass
GPIO-1	All resistances > 10M Ω	Pass
GPIO-2	All resistances > 10M Ω	Pass
GPIO-3	All resistances > 10M Ω	Pass
GPIO-4	All resistances > 10M Ω	Pass
GPIO-5	All resistances > 10M Ω	Pass
GPIO-6	All resistances > 10M Ω	Pass
GPIO-7	All resistances > 10M Ω	Pass